SLVS178B - DECEMBER 1998 - REVISED MAY 2001

- 100-mA Low-Dropout Regulator
- Fixed Output Voltage Options: 5 V, 3.8 V, 3.3 V, 3.2 V, and 3 V
- Dropout Typically 170 mV at 100-mA
- Thermal Protection
- Less Than 1 μA Quiescent Current in Shutdown
- -40°C to 125°C Operating Junction Temperature Range
- 5-Pin SOT-23 (DBV) Package
- ESD Protection Verified to 1.5 KV Human Body Model (HBM) per MIL-STD-883C

DBV PACKAGE (TOP VIEW) EN GND IN 3 2 1 4 5 NC OUT

NC - No internal connection

description

The TPS761xx is a 100 mA, low dropout (LDO) voltage regulator designed specifically for battery-powered applications. A proprietary BiCMOS fabrication process allows the TPS761xx to provide outstanding performance in all specifications critical to battery-powered operation.

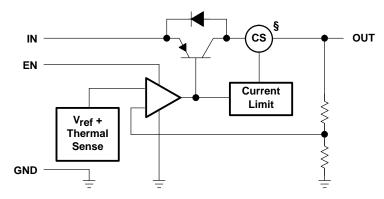
The TPS761xx is available in a space-saving SOT-23 (DBV) package and operates over a junction temperature range of –40°C to 125°C.

AVAILABLE OPTIONS

TJ	VOLTAGE	PACKAGE	PART N	UMBER	SYMBOL
	3 V		TPS76130DBVR [†]	TPS76130DBVT‡	PAEI
	3.2 V	SOT-23 (DBV)	TPS76132DBVR [†]	TPS76132DBVT‡	PAFI
-40°C to 125°C	3.3 V		TPS76133DBVR [†]	TPS76133DBVT‡	PAII
	3.8 V	(554)	TPS76138DBVR [†]	TPS76138DBVT‡	PAKI
	5 V		TPS76150DBVR†	TPS76150DBVT‡	PALI

[†]The DBVR passive indicates tape and reel of 3000 parts.

functional block diagram



§ Current sense



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



[‡]The DBVT passive indicates tape and reel of 250 parts.

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Terminal Functions

TERM	TERMINAL		DESCRIPTION									
NAME	NO.	1/0	DESCRIPTION									
EN	3	I	Enable input									
GND	2		Ground									
IN	1	I	Input voltage									
NC	4		No connection									
OUT	5	0	Regulated output voltage									

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Input voltage range, V _I (see Note 1)	–0.3 V to 16 V
Voltage range at EN	0.3 V to V _I + 0.3 V
Peak output current	internally limited
Continuous total dissipation	See Dissipation Rating Table
Operating junction temperature range, T _J	–40°C to 150°C
Storage temperature range, T _{stq}	–65°C to 150°C
ESD rating, HBM	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltages are with respect to device GND pin.

DISSIPATION RATING TABLE

BOARD	PACKAGE	$R_{ heta}$ JC	$R_{ heta JA}$	DERATING FACTOR ABOVE T _A = 25°C	$T_A \le 25^{\circ}C$ POWER RATING	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING	
Low K‡	DBV	65.8 °C/W	259 °C/W	3.9 mW/°C	386 mW	212 mW	154 mW	
High K§	DBV	65.8 °C/W	180 °C/W	5.6 mW/°C	555 mW	305 mW	222 mW	

[‡] The JEDEC Low K (1s) board design used to derive this data was a 3 inch x 3 inch, two layer board with 2 ounce copper traces on top of the board. § The JEDEC High K (2s2p) board design used to derive this data was a 3 inch x 3 inch, multilayer board with 1 ounce internal power and ground planes and 2 ounce copper traces on top and bottom of the board.

recommended operating conditions

		MIN	NOM MAX	UNIT
Input voltage, V _I	TPS76130	3.35	16	
	TPS76132	3.58	16	1
	TPS76133	3.68	16	V
	TPS76138	4.18	16	1
	TPS76150	5.38	16	
Continuous output current, I)	0	100	mA
Operating junction temperate	ıre, TJ	-40	125	°C

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electrical characteristics over recommended operating free-air temperature range, V_I = V_{O(typ)} + 1 V, I_O = 1 mA, EN = V_I, C_o = 4.7 μ F (unless otherwise noted)

	PARAMETER		TEST CO	MIN	TYP	MAX	UNIT				
			T _J = 25°C		2.96	3	3.04				
		TPS76130	T _J = 25°C,	1 mA < I _O < 100 mA	2.9		3.04	V			
			1 mA < I _O < 100 mA		2.89		3.07				
			T _J = 25°C	3.16	3.2	3.24					
		TPS76132	T _J = 25°C,	1 mA < I _O < 100 mA	3.11		3.24	4 V			
			1 mA < I _O < 100 mA		3.08		3.3				
			T _J = 25°C		3.26	3.3	3.34				
٧o	Output voltage	TPS76133	T _J = 25°C,	1 mA < I _O < 100 mA	3.21		3.34	V			
			1 mA < I _O < 100 mA		3.18		3.4				
			T _J = 25°C		3.76	3.8	3.84				
		TPS76138	T _J = 25°C,	1 mA < I _O < 100 mA	3.71		3.84	V			
			1 mA < I _O < 100 mA		3.68		3.9				
			T _J = 25°C		4.95	5	5.05	V			
		TPS76150	T _J = 25°C,	1 mA < I _O < 100 mA	4.88		5.05				
			1 mA < I _O < 100 mA		4.86		5.1	1			
I _{I(standby)}	Standby current		EN = 0 V				1	μΑ			
($I_O = 0 \text{ mA},$	T _J = 25°C		90	115				
			$I_O = 0 \text{ mA}$			130					
			I _O = 1 mA,	T _J = 25°C		100	130				
			I _O = 1 mA				170				
	0:	NID ()	I _O = 10 mA,	T _J = 25°C		190	220				
	Quiescent current (G	SND current)	I _O = 10 mA				260	μΑ			
			I _O = 50 mA,	T _J = 25°C		850	1100				
			I _O = 50 mA				1200	1			
			I _O = 100 mA,	T _J = 25°C		2600	3600	1			
			I _O = 100 mA				4000				
		TPS76130	4 V < V _I < 16,	I _O = 1 mA		3	10				
		TPS76132	4.2 V < V _I < 16,	I _O = 1 mA		3	10				
	Input regulation	TPS76133	4.3 V < V _I < 16,	I _O = 1 mA		3	10	mV			
		TPS76138	4.8 V < V _I < 16,	I _O = 1 mA		3	10				
		TPS76150	6 V < V _I < 16	I _O = 1 mA		3	10				
Vn	Output noise voltage		BW = 300 Hz to 50 kHz	$C_0 = 10 \mu\text{F}, \text{T}_J = 25^{\circ}\text{C}$		190		μVrms			
	Ripple rejection		$f = 1 \text{ kHz}, C_0 = 10 \mu\text{F},$			63		dB			

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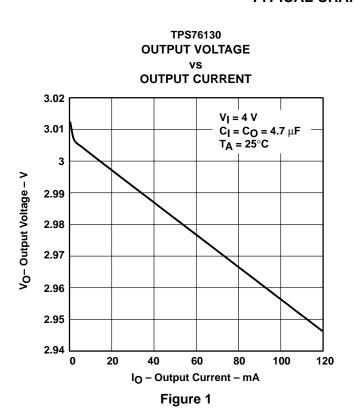
electrical characteristics over recommended operating free-air temperature range, $V_I = V_{O(typ)} + 1 \text{ V}$, $I_O = 1 \text{ mA}$, $EN = V_I$, $C_O = 4.7 \, \mu\text{F}$ (unless otherwise noted) (continued)

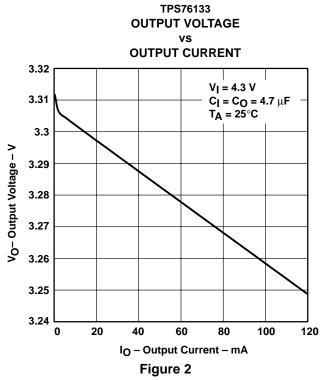
PARAMETER	TEST CONDITIONS	MIN TYP I	MAX UNIT
	$I_O = 0 \text{ mA},$ $T_J = 25^{\circ}\text{C}$	1	3
	$I_O = 0 \text{ mA}$		5
	$I_O = 1 \text{ mA},$ $T_J = 25^{\circ}\text{C}$	7	10
	I _O = 1 mA		15
Dropout voltage	$I_O = 10 \text{ mA},$ $T_J = 25^{\circ}\text{C}$	40	60 mV
Dropout voltage	I _O = 10 mA		90
	$I_O = 50 \text{ mA},$ $T_J = 25^{\circ}\text{C}$	120	150
	$I_O = 50 \text{ mA}$		180
	$I_{O} = 100 \text{ mA}, T_{J} = 25^{\circ}\text{C}$	170	240
	I _O = 100 mA		280
Peak output current/current limit		100 125	135 mA
High level enable input		2	V
Low level enable input			0.8 V
I. Input surrent (FNI)	EN = 0 V	-1 0	1
II Input current (EN)	EN = V _I	2.5	μA

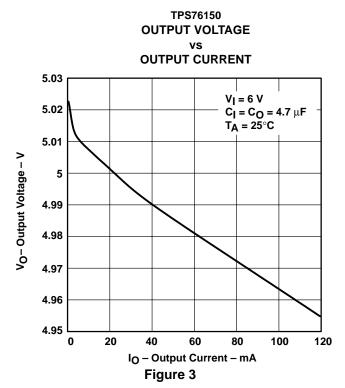
TYPICAL CHARACTERISTICS

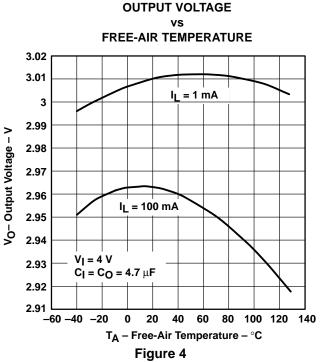
Table of Graphs

			FIGURE
\/ ₋	Output voltage	vs Output current	1, 2, 3
Vo	Output voltage	vs Free-air temperature	4, 5, 6
	Ground current	vs Free-air temperature	7, 8, 9
	Output noise	vs Frequency	10
Zo	Output impedance	vs Frequency	11
VDO	Dropout voltage	vs Free-air temperature	12
	Line transient response		13, 15
	Load transient response		14, 16

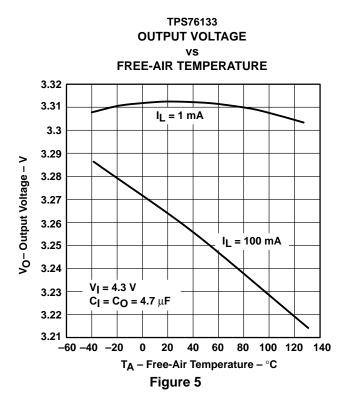


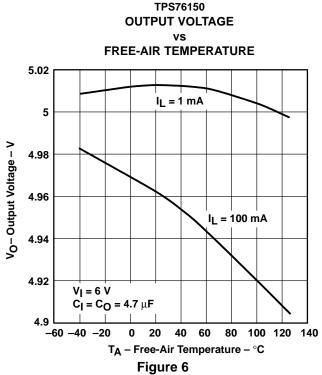






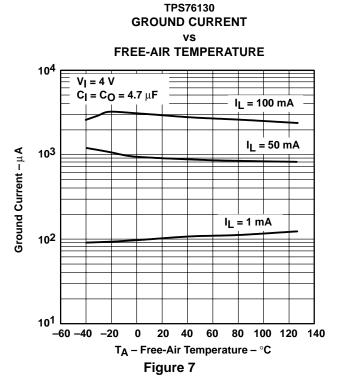
TPS76130

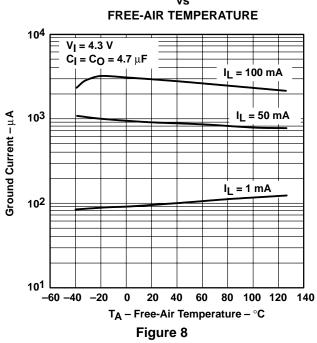


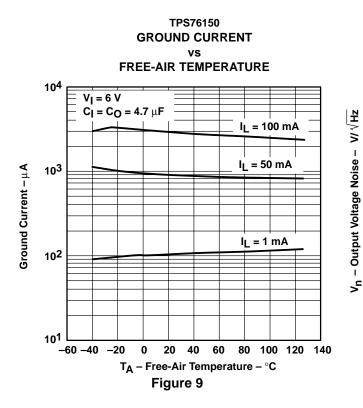


TPS76133

GROUND CURRENT







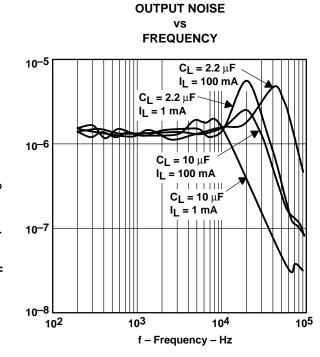
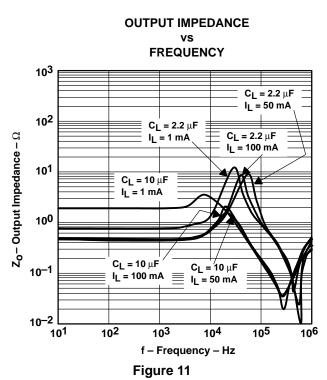
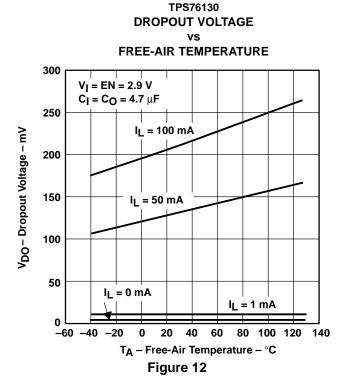


Figure 10





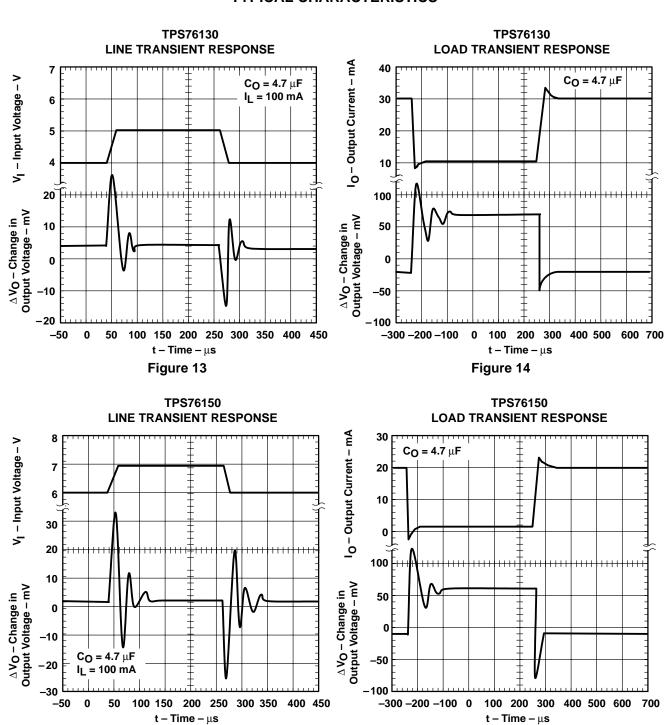




Figure 16

Figure 15

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APPLICATION INFORMATION

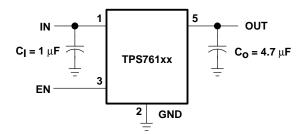


Figure 17. TPS761xx Typical Application

over current protection

The over current protection circuit forces the TPS761xx into a constant current output mode when the load is excessive or the output is shorted to ground. Normal operation resumes when the fault condition is removed.

NOTE:

An overload or short circuit may also activate the over temperature protection if the fault condition persists.

over temperature protection

The thermal protection system shuts the TPS761xx down when the junction temperature exceeds 160°C. The device recovers and operates normally when the temperature drops below 150°C.

input capacitor

A 1- μ F or larger ceramic decoupling capacitor with short leads connected between IN and GND is recommended. The decoupling capacitor may be omitted if there is a 1 μ F or larger electrolytic capacitor connected between IN and GND and located reasonably close to the TPS761xx. However, the small ceramic device is desirable even when the larger capacitor is present, if there is a lot of high frequency noise present in the system.

output capacitor

Like all low dropout regulators, the TPS761xx requires an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance value is 4.7 μ F and the ESR (equivalent series resistance) must be between 0.1 Ω and 10 Ω . Solid tantalum electrolytic, aluminum electrolytic, and multilayer ceramic capacitors are all suitable, provided they meet the requirements described above. Most of the commercially available 4.7- μ F surface-mount solid-tantalum capacitors, including devices from Sprague, Kemet, and Nichicon, meet the ESR requirements stated above. Multilayer ceramic capacitors should have minimum values of 4.7 μ F over the full operating temperature range of the equipment.

enable (EN)

A logic zero on the enable input shuts the TPS761xx off and reduces the supply current to less than 1 μ A. Pulling the enable input high causes normal operation to resume. If the enable feature is not used, EN should be connected to IN to keep the regulator on all of the time. The EN input must not be left floating.

reverse current path

The power transistor used in the TPS761xx has an inherent diode connected between IN and OUT as shown in the functional block diagram. This diode conducts current from the OUT terminal to the IN terminal whenever IN is lower than OUT by a diode drop. This condition does not damage the TPS761xx provided the current is limited to 150 mA.







24-Jan-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
TPS76130DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAEI	Sample
TPS76130DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAEI	Sample
TPS76130DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAEI	Sample
TPS76130DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAEI	Sample
TPS76132DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAFI	Sample
TPS76132DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAFI	Sample
TPS76132DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAFI	Sample
TPS76132DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAFI	Sample
TPS76133DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAII	Sample
TPS76133DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAII	Sample
TPS76133DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAII	Sample
TPS76133DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAII	Sample
TPS76138DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAKI	Sample
TPS76138DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAKI	Sample
TPS76138DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAKI	Sample
TPS76138DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAKI	Sample
TPS76150DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PALI	Sample



PACKAGE OPTION ADDENDUM

24-Jan-2013

Orderable Device	Status	Package Type	Package	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing			(2)		(3)		(4)	
TPS76150DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	I	PALI	Samples
TPS76150DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	I	PALI	Samples
TPS76150DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PALI	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): Tl's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Ph-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder humps used between the die and package, or 2) lead-based die adhesive used between

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



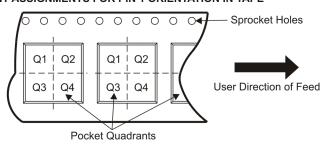
TAPE AND REEL INFORMATION



TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

		Dimension designed to accommodate the component width
		Dimension designed to accommodate the component length
		Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
Г	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS76130DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76130DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76132DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76132DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76133DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76133DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76138DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76138DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76150DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76150DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3



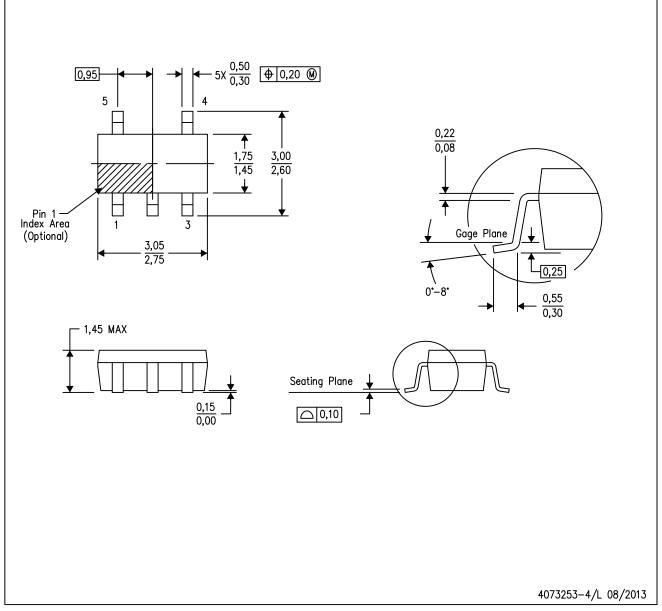


*All dimensions are nominal

All difficultions are nominal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS76130DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS76130DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS76132DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS76132DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS76133DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS76133DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS76138DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS76138DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS76150DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS76150DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



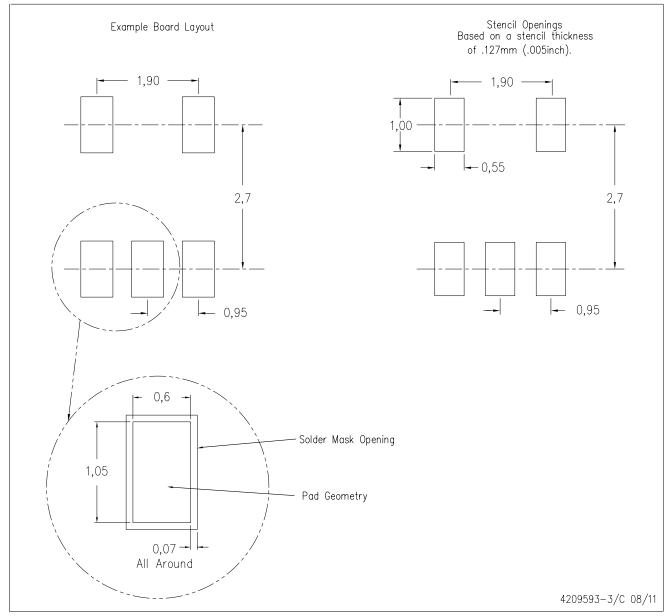
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-178 Variation AA.



DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



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